

TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP TPS77525-EP, TPS77533-EP WITH $\overline{\text{RESET}}$ OUTPUT FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS

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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of -55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **Open Drain Power-On Reset With 200-ms Delay**
- **500-mA Low-Dropout Voltage Regulator**
- **Available in 1.5-V, 1.6-V, 1.8-V, 2.5-V, 3.3-V Fixed Output and Adjustable Versions**
- **Dropout Voltage to 169 mV (Typ) at 500 mA (TPS77533)**
- **Ultralow 85 μA Typical Quiescent Current**
- **Fast Transient Response**
- **2% Tolerance Over Specified Conditions for Fixed-Output Versions**
- **20-Pin TSSOP PowerPAD™ (PWP) Package**
- **Thermal Shutdown Protection**

**PWP PACKAGE
(TOP VIEW)**

| | | | |
|-----------|----|----|---------------------------|
| GND/HSINK | 1 | 20 | GND/HSINK |
| GND/HSINK | 2 | 19 | GND/HSINK |
| GND | 3 | 18 | NC |
| NC | 4 | 17 | NC |
| EN | 5 | 16 | $\overline{\text{RESET}}$ |
| IN | 6 | 15 | FB/NC |
| IN | 7 | 14 | OUT |
| NC | 8 | 13 | OUT |
| GND/HSINK | 9 | 12 | GND/HSINK |
| GND/HSINK | 10 | 11 | GND/HSINK |

NC – No internal connection

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description

The TPS775xx devices are designed to have a fast transient response and be stable with a 10- μF low ESR capacitors. This combination provides high performance at a reasonable cost.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 169 mV at an output current of 500 mA for the TPS77533) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μA over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to 1 μA at $T_J = 25^{\circ}\text{C}$.

The $\overline{\text{RESET}}$ output of the TPS775xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS775xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

The TPS775xx is offered in 1.5-V, 1.6-V, 1.8-V, 2.5-V, and 3.3-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V for TPS77501 option). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS775xx family is available in 20 pin TSSOP package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

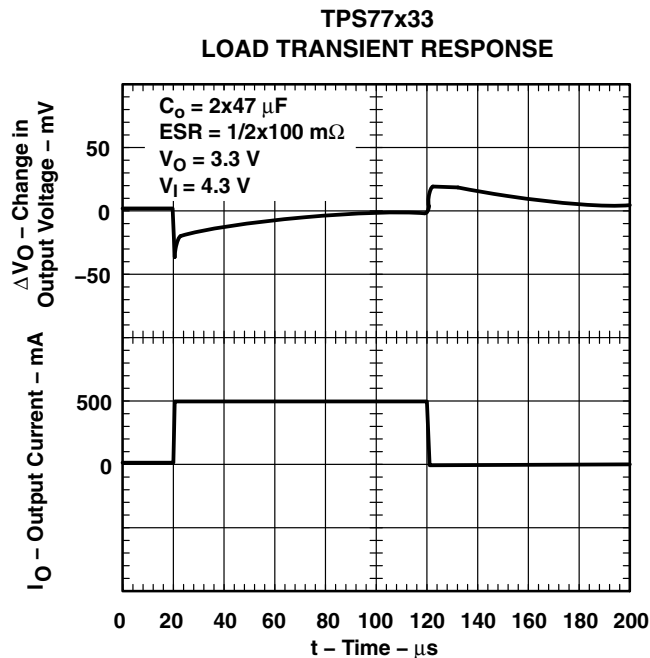
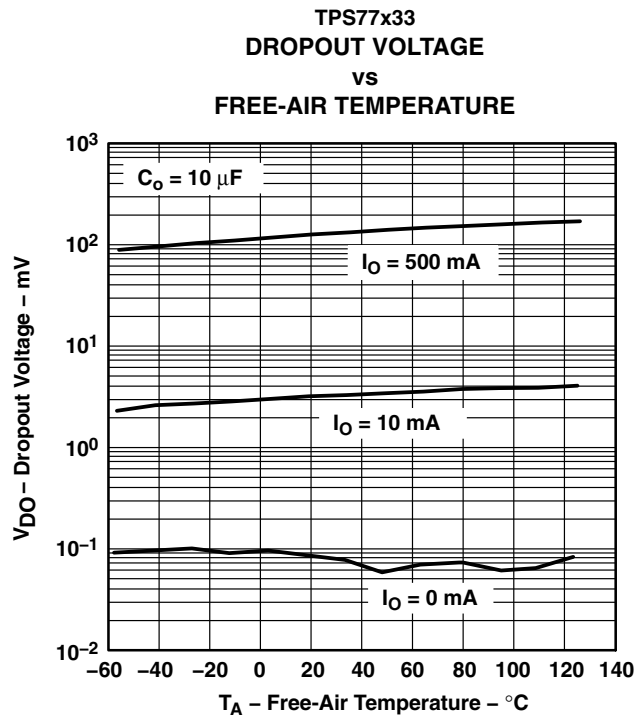


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**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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ORDERING INFORMATION†

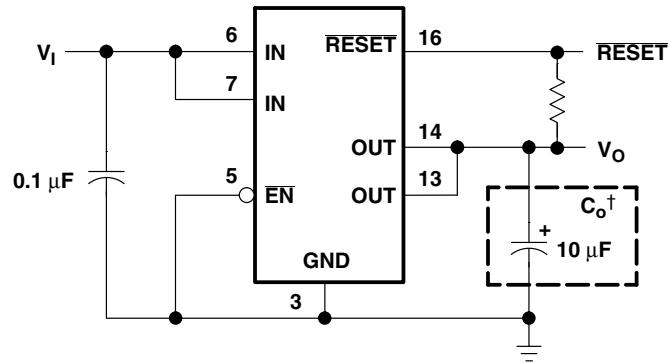
| T_A | OUTPUT VOLTAGE (V TYP) | PACKAGE | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-------------------------------|------------|---------------|-----------------------|------------------|
| -55°C to 125°C | 3.3 | TSSOP – PW | Tape and reel | TPS77533MPWPREP | 77533ME |
| | 2.5 | TSSOP – PW | Tape and reel | TPS77525MPWPREP | 77525ME |
| | 1.8 | TSSOP – PW | Tape and reel | TPS77518MPWPREP | 77518ME |
| | 1.6 | TSSOP – PW | Tape and reel | TPS77516MPWPREP§ | 77516ME |
| | 1.5 | TSSOP – PW | Tape and reel | TPS77515MPWPREP | 77515ME |
| | Adjustable‡ 1.5 V to 5.5 V | TSSOP – PW | Tape and reel | TPS77501MPWPREP | 77501ME |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ The TPS77501 is programmable using an external resistor divider (see application information).

§ TPS77516 is Product Preview.

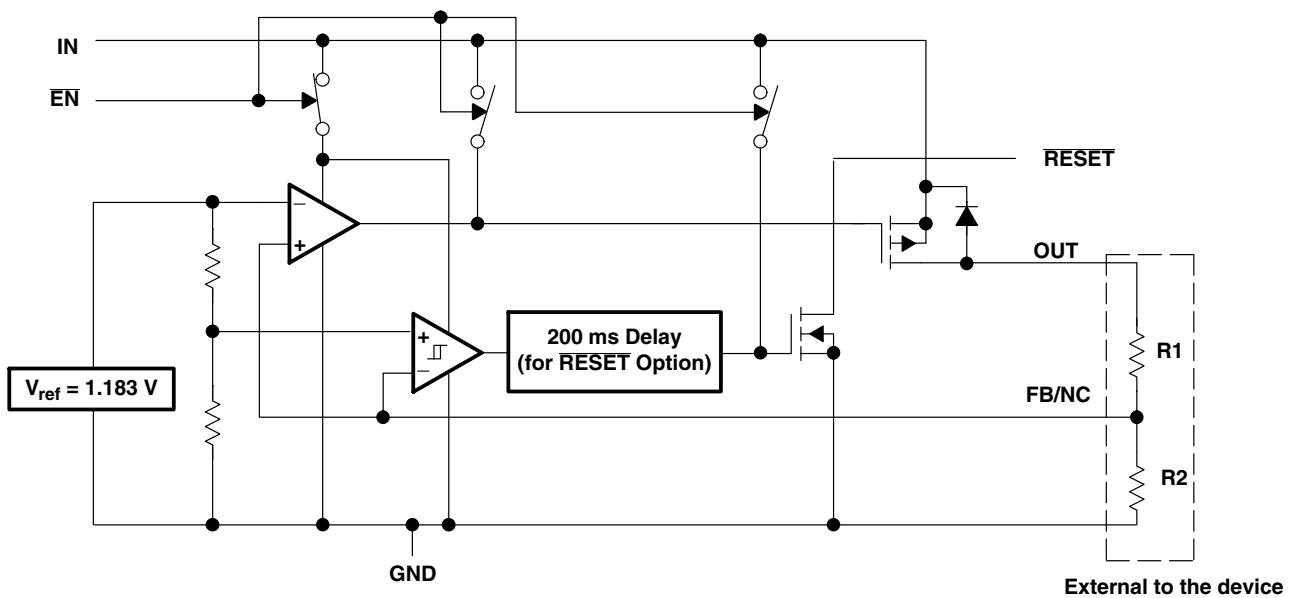
**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH $\overline{\text{RESET}}$ OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**
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† See application information section for capacitor selection details.

Figure 1. Typical Application Configuration for Fixed Output Options

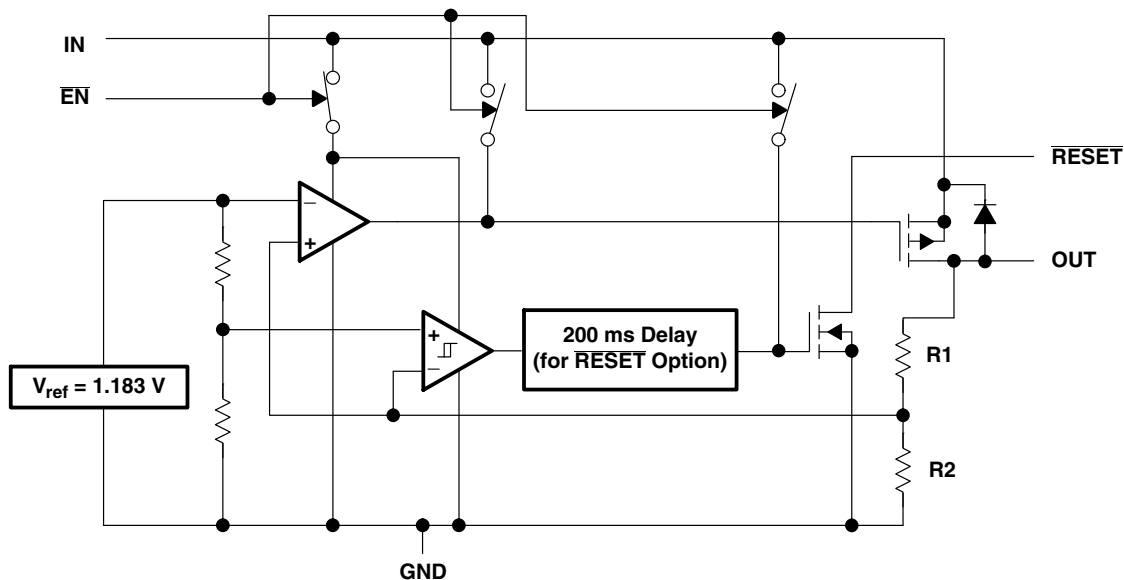
functional block diagram—adjustable version



**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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functional block diagram—fixed-voltage version



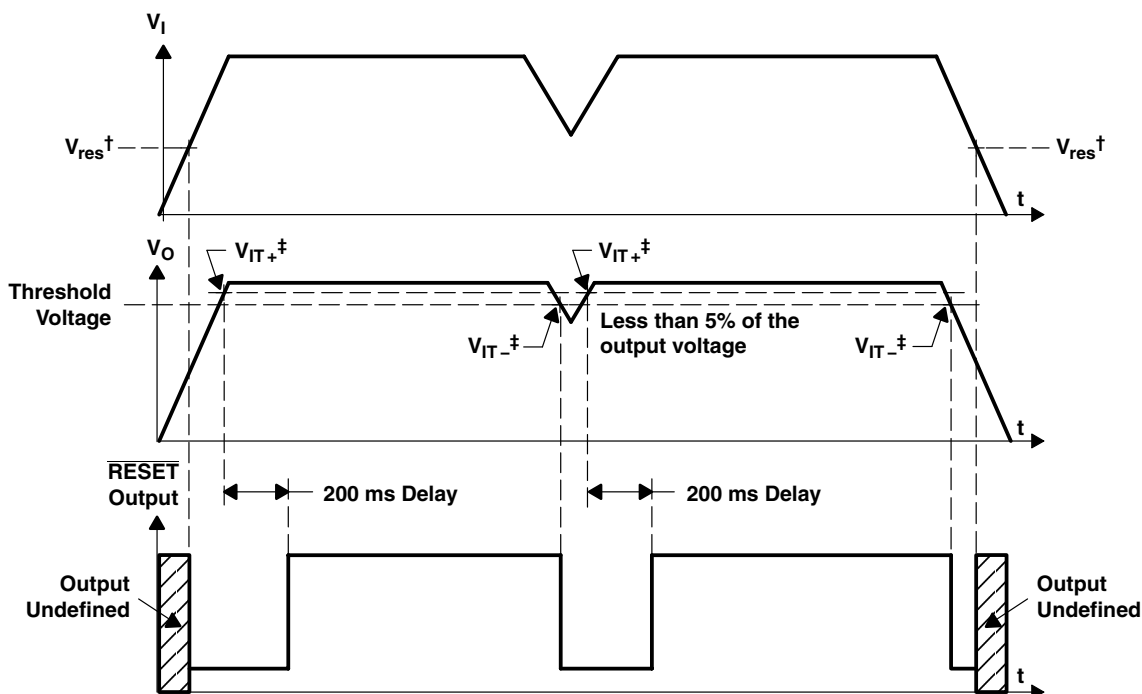
Terminal Functions

TSSOP Package

| TERMINAL NAME | NO. | I/O | DESCRIPTION |
|------------------|--------------------------------|-----|---|
| EN | 5 | I | Enable input |
| FB/NC | 15 | I | Feedback input voltage for adjustable device (no connect for fixed options) |
| GND | 3 | | Regulator ground |
| GND/HSINK | 1, 2, 9, 10, 11, 12, 19, 20 | | Ground/heatsink |
| IN | 6, 7 | I | Input voltage |
| NC | 4, 8, 17, 18 | | No connect |
| OUT | 13, 14 | O | Regulated output voltage |
| RESET | 16 | O | RESET output |

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
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RESET timing diagram



$^\dagger V_{res}$ is the minimum input voltage for a valid RESET. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

$^\ddagger V_{IT}$ – Trip voltage is typically 5% lower than the output voltage ($95\%V_O$). V_{IT-} to V_{IT+} is the hysteresis voltage.

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
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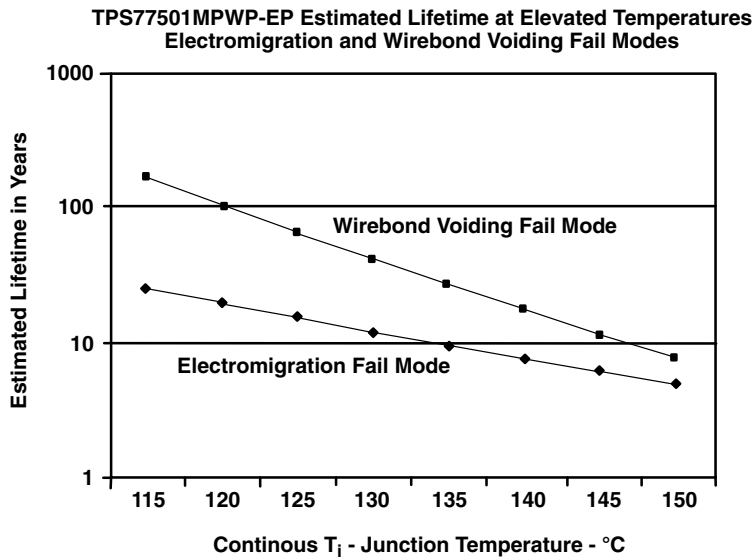
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|---|-------------------------------|
| Input voltage range [‡] , V_I | –0.3 V to 13.5 V |
| Voltage range at \overline{EN} | –0.3 V to 16.5 V |
| Maximum RESET voltage | 16.5 V |
| Peak output current | Internally limited |
| Output voltage, V_O (OUT, FB) | 7 V |
| Continuous total power dissipation | See dissipation rating tables |
| Maximum junction temperature, T_J | 125°C |
| Thermal impedance, junction to ambient [§] , θ_{JA} | 32.63°C/W |
| Thermal impedance, junction to current [§] , θ_{JC} | 1.4°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |
| ESD rating, HBM | 2 kV |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡] All voltage values are with respect to network terminal ground.

[§] Package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions

| | MIN | MAX | UNIT |
|--|-----|-----|------|
| Input voltage, V_I [#] | 2.7 | 10 | V |
| Output voltage range, V_O | 1.5 | 5.5 | V |
| Output current, I_O (see Note 1) | 0 | 500 | mA |
| Operating virtual junction temperature, T_J (see Note 1) | –55 | 125 | °C |

[#] To calculate the minimum input voltage for your maximum output current, use the following equation: $V_{I(min)} = V_{O(max)} + V_{DO(max\ load)}$.

NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
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electrical characteristics over recommended operating free-air temperature range,
 $V_I = V_{O(typ)} + 1\text{ V}$, $I_O = 1\text{ mA}$, $\overline{\text{EN}} = 0\text{ V}$, $C_O = 10\text{ }\mu\text{F}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|--|----------|---|--|--------------------|--------------------|-----|-------|
| Output voltage (10 μA to 500 mA load) (see Note 2) | TPS77501 | 1.5 V ≤ V _O ≤ 5.5 V, T _J = 25°C | | V _O | | | V |
| | | 1.5 V ≤ V _O ≤ 5.5 V, T _J = −55°C to 125°C | | 0.98V _O | 1.02V _O | | |
| | TPS77515 | T _J = 25°C, 2.7 V < V _{IN} < 10 V | | 1.5 | | | |
| | | T _J = −55°C to 125°C, 2.7 V < V _{IN} < 10 V | | 1.470 | 1.530 | | |
| | TPS77516 | T _J = 25°C, 2.7 V < V _{IN} < 10 V | | 1.6 | | | V |
| | | T _J = −55°C to 125°C, 2.7 V < V _{IN} < 10 V | | 1.568 | 1.632 | | |
| | TPS77518 | T _J = 25°C, 2.8 V < V _{IN} < 10 V | | 1.8 | | | V |
| | | T _J = −55°C to 125°C, 2.8 V < V _{IN} < 10 V | | 1.764 | 1.836 | | |
| | TPS77525 | T _J = 25°C, 3.5 V < V _{IN} < 10 V | | 2.5 | | | |
| | | T _J = −55°C to 125°C, 3.5 V < V _{IN} < 10 V | | 2.450 | 2.550 | | |
| | TPS77533 | T _J = 25°C, 4.3 V < V _{IN} < 10 V | | 3.3 | | | |
| | | T _J = −55°C to 125°C, 4.3 V < V _{IN} < 10 V | | 3.234 | 3.366 | | |
| Quiescent current (GND current) EN = 0V, (see Note 2) | | 10 μA < I _O < 500 mA, T _J = 25°C | | 85 | | | μA |
| | | I _O = 500 mA, T _J = −55°C to 125°C | | | | 125 | |
| Output voltage line regulation (ΔV _O /V _O) (see Notes 2 and 3) | | V _O + 1 V < V _I ≤ 10 V, T _J = 25°C | | 0.01 | | | %/V |
| Load regulation | | | | 3 | | | mV |
| Output noise voltage (TPS77518) | | BW = 200 Hz to 100 kHz, I _C = 500 mA C _O = 10 μF, T _J = 25°C | | 53 | | | μVrms |
| Output current limit | | V _O = 0 V | | 1.7 | | 2.4 | A |
| Thermal shutdown junction temperature | | | | 150 | | | °C |
| Standby current | | EN = V _I , T _J = 25°C, 2.7 V < V _I < 10 V | | 1 | | | μA |
| | | EN = V _I , T _J = −55°C to 125°C 2.7 V < V _I < 10 V | | | | 10 | μA |
| FB input current | TPS77501 | FB = 1.5 V | | 2 | | | nA |
| High level enable input voltage | | | | 1.7 | | | V |
| Low level enable input voltage | | | | | | 0.9 | V |
| Power supply ripple rejection (see Note 2) | | f = 1 KHz, C _O = 10 μF, T _J = 25°C | | 60 | | | dB |

NOTES: 2. Minimum IN operating voltage is 2.7 V or $V_{O(typ)} + 1\text{ V}$, whichever is greater. Maximum IN voltage 10 V .

3. If $V_O \leq 1.8\text{ V}$ then $V_{Imin} = 2.7\text{ V}$, $V_{Imax} = 10\text{ V}$:

$$\text{Line Reg. (mV)} = (\%/V) \times \frac{V_O(V_{Imax} - 2.7\text{ V})}{100} \times 1000$$

If $V_O \geq 2.5\text{ V}$ then $V_{Imin} = V_O + 1\text{ V}$, $V_{Imax} = 10\text{ V}$:

$$\text{Line Reg. (mV)} = (\%/V) \times \frac{V_O(V_{Imax} - (V_O + 1\text{ V}))}{100} \times 1000$$

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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**electrical characteristics over recommended operating free-air temperature range,
 $V_I = V_{O(typ)} + 1\text{ V}$, $I_O = 1\text{ mA}$, $\overline{\text{EN}} = 0\text{ V}$, $C_O = 10\text{ }\mu\text{F}$ (unless otherwise noted) (continued)**

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---------------------------------------|---|------|-----|-----|---------------|
| Reset | Minimum input voltage for valid RESET | $I_{O(RESET)} = 300\text{ }\mu\text{A}$ | | 1.1 | | V |
| | Trip threshold voltage | V_O decreasing | 92 | | 98 | % V_O |
| | Hysteresis voltage | Measured at V_O | | 0.5 | | % V_O |
| | Output low voltage | $V_I = 2.7\text{ V}$, $I_{O(RESET)} = 1\text{ mA}$ | 0.15 | | 0.4 | V |
| | Leakage current | $V_{(RESET)} = 5\text{ V}$ | | | 1 | μA |
| | RESET time-out delay | | | 200 | | ms |
| Input current ($\overline{\text{EN}}$) | | $\overline{\text{EN}} = 0\text{ V}$ | -1 | 0 | 1 | μA |
| | | $\overline{\text{EN}} = V_I$ | -1 | | 1 | |
| Dropout voltage (see Note 4) | TPS77533 | $I_O = 500\text{ mA}$, $T_J = 25^\circ\text{C}$ | | 169 | | mV |
| | | $I_O = 500\text{ mA}$, $T_J = -55^\circ\text{C to } 125^\circ\text{C}$ | | | 287 | |

NOTE 4: I_N voltage equals $V_{O(typ)} - 100\text{ mV}$; TPS77515, TPS77516, TPS77518, and TPS77525 dropout voltage limited by input voltage range limitations (i.e., TPS77533 input voltage needs to drop to 3.2 V for purpose of this test).

TYPICAL CHARACTERISTICS

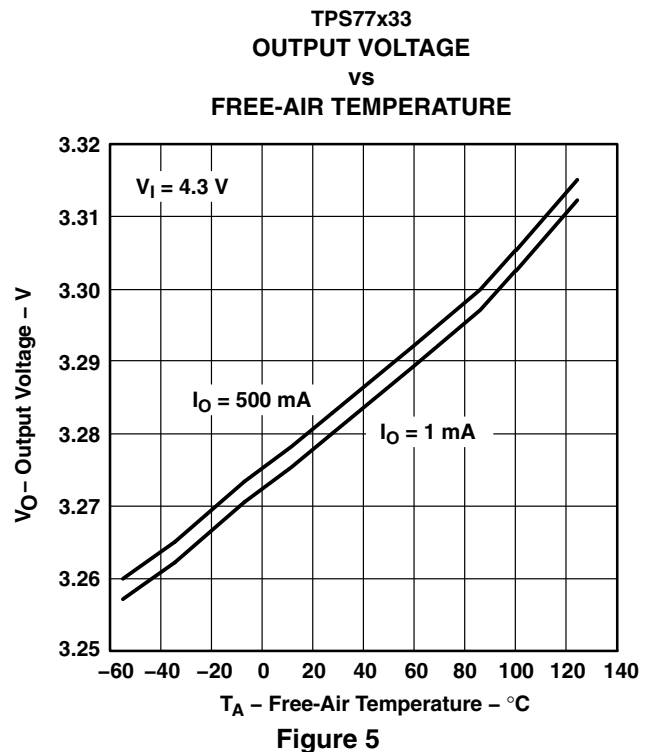
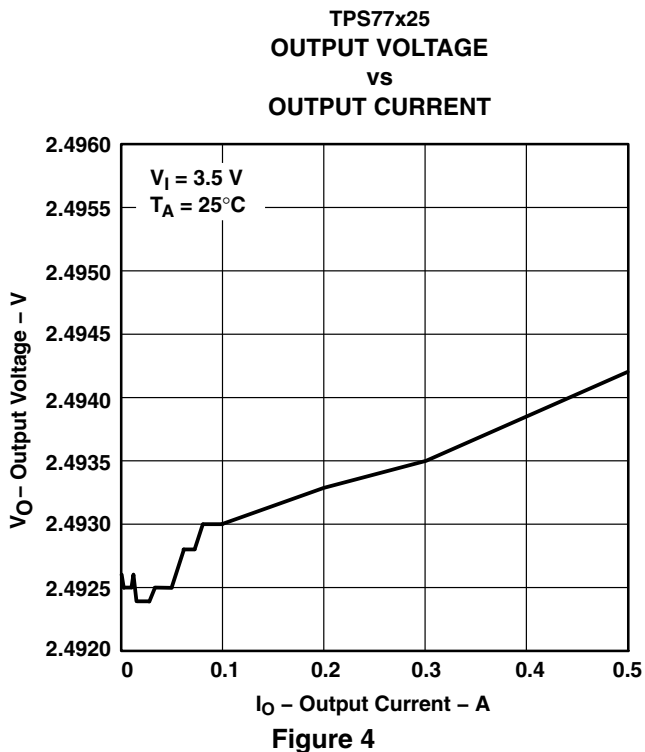
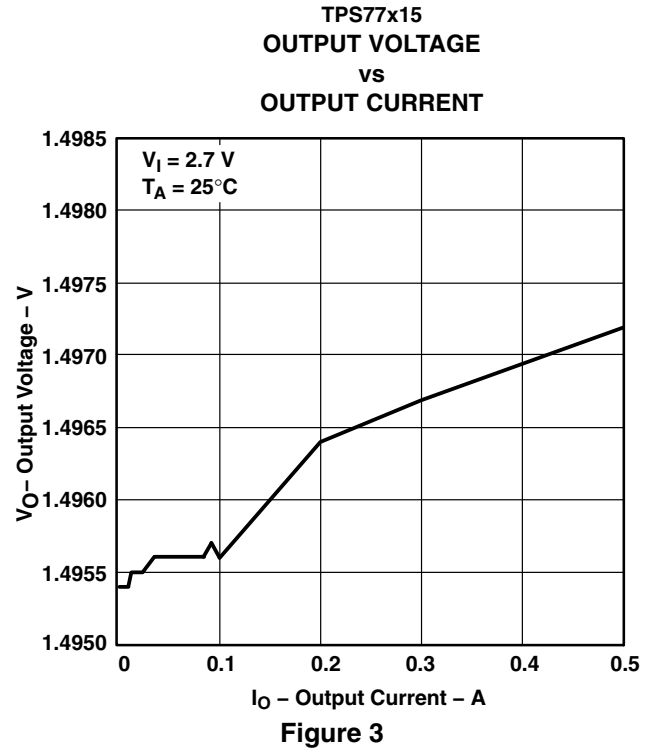
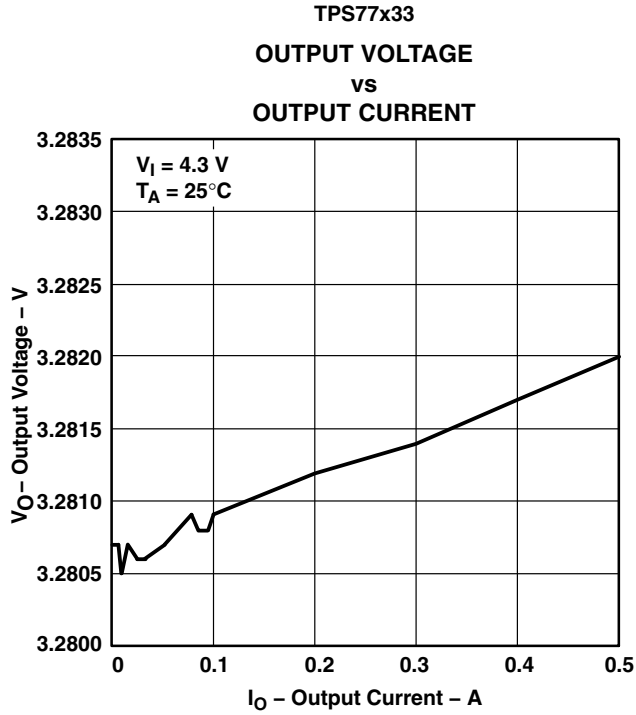
Table of Graphs

| | | | FIGURE |
|----------|------------------------------------|-------------------------|---------|
| V_O | Output voltage | vs Output current | 2, 3, 4 |
| | | vs Free-air temperature | 5, 6, 7 |
| | Ground current | vs Free-air temperature | 8 |
| | Power supply ripple rejection | vs Frequency | 9 |
| | Output spectral noise density | vs Frequency | 10 |
| Z_O | Output impedance | vs Frequency | 11 |
| V_{DO} | Dropout voltage | vs Input voltage | 12 |
| | | vs Free-air temperature | 13 |
| | Input voltage (min) | vs Output voltage | 14 |
| | Line transient response | | 15, 17 |
| | Load transient response | | 16, 18 |
| V_O | Output voltage | vs Time | 19 |
| | Equivalent series resistance (ESR) | vs Output current | 21 – 24 |

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
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TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

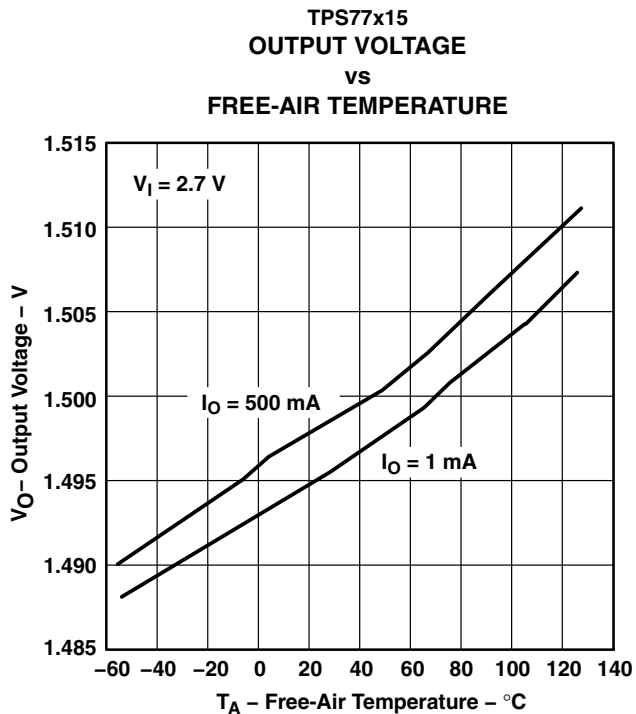


Figure 6

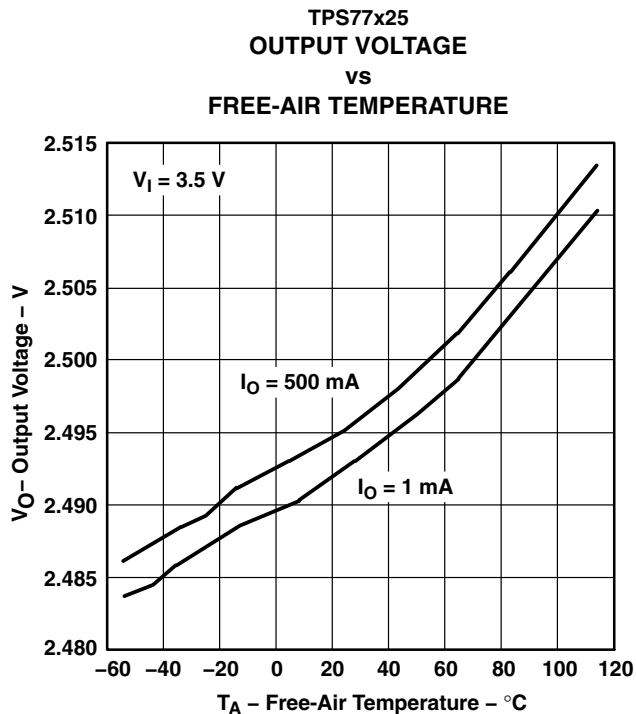


Figure 7

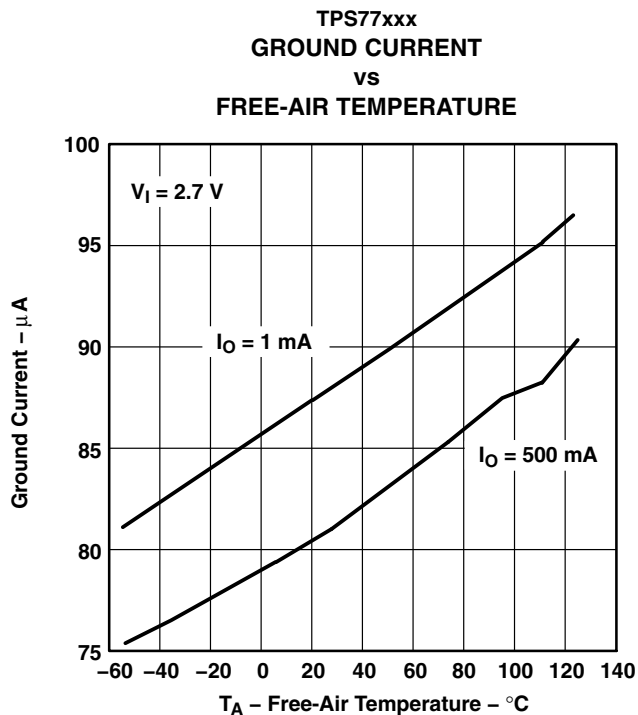


Figure 8

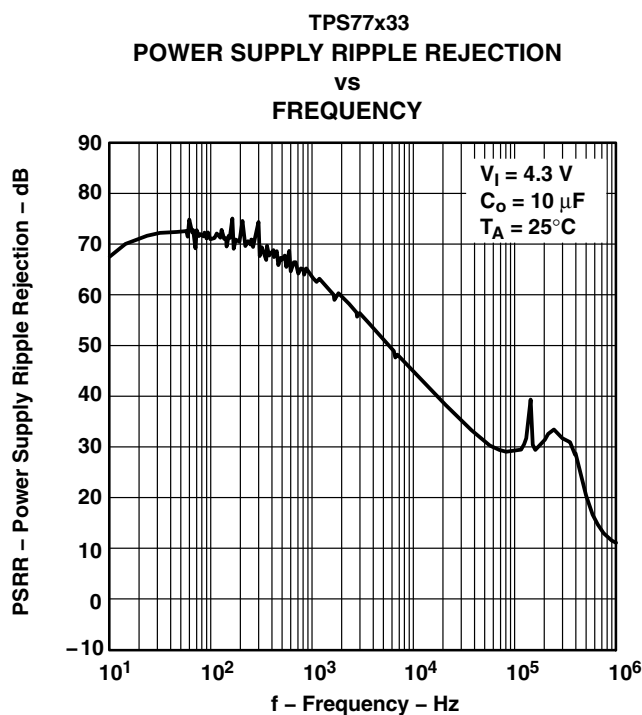
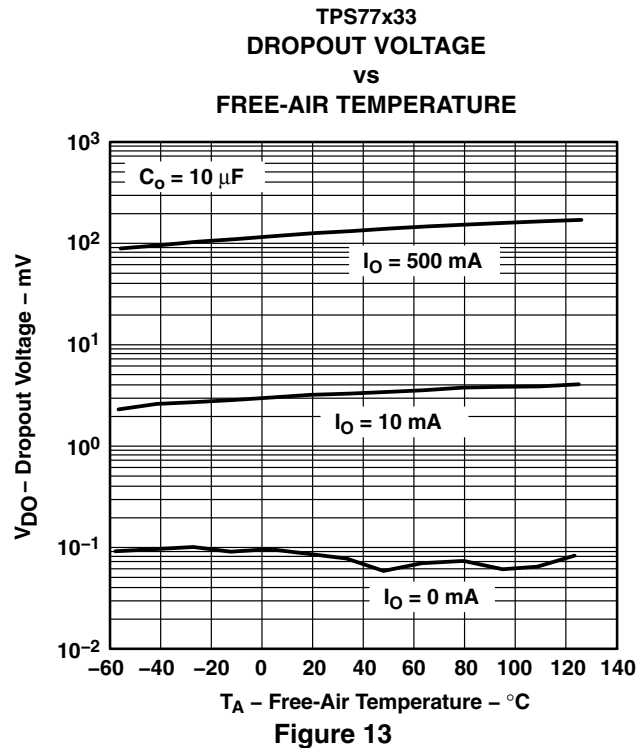
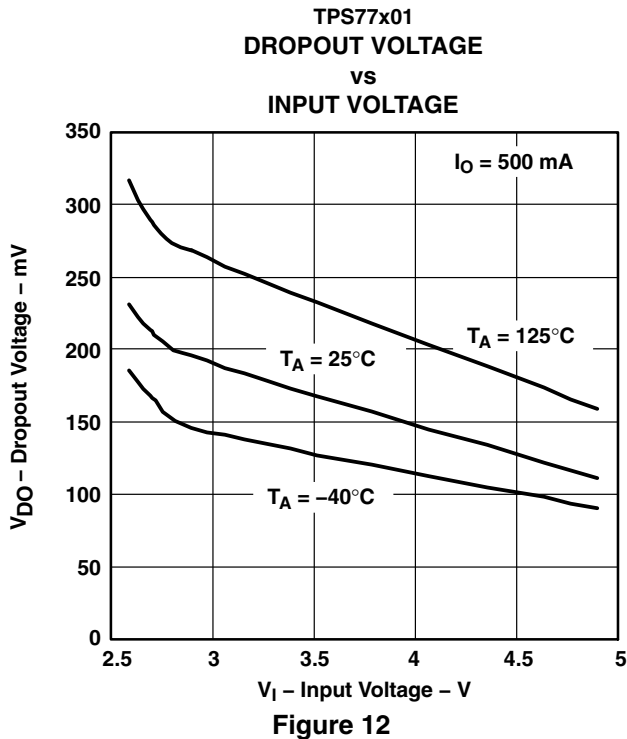
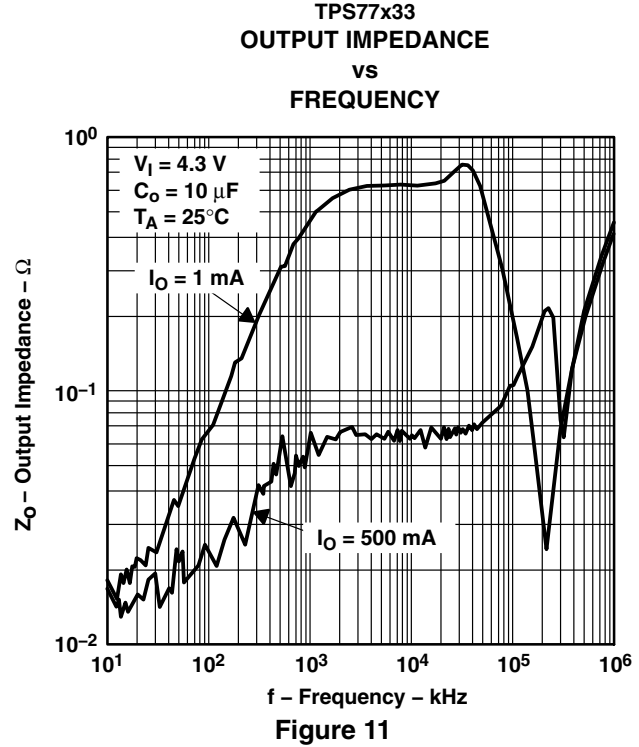
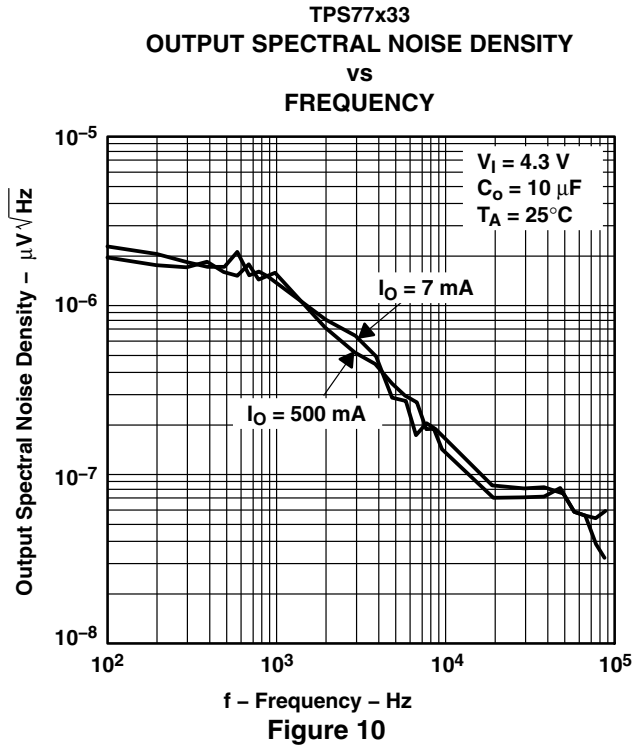


Figure 9

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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TYPICAL CHARACTERISTICS



**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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TYPICAL CHARACTERISTICS

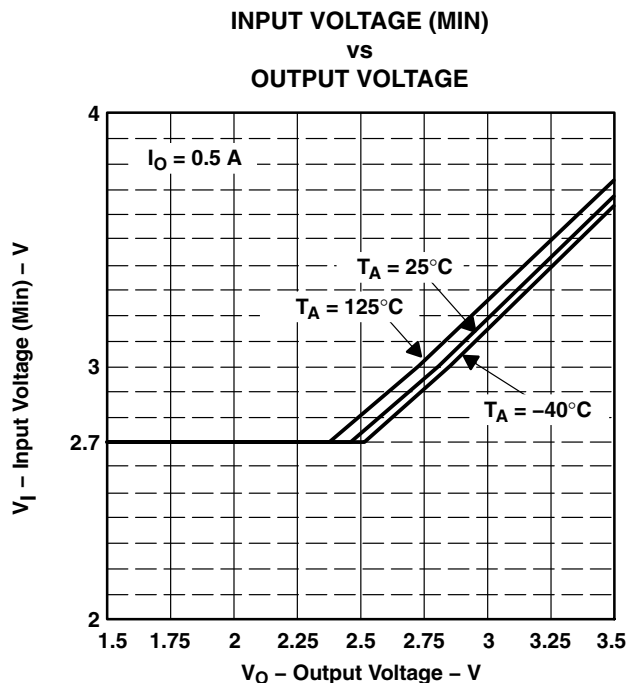


Figure 14

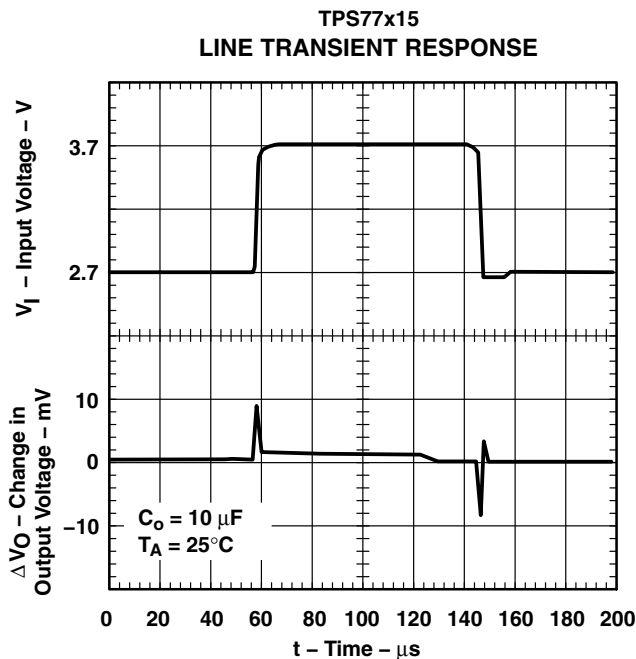


Figure 15

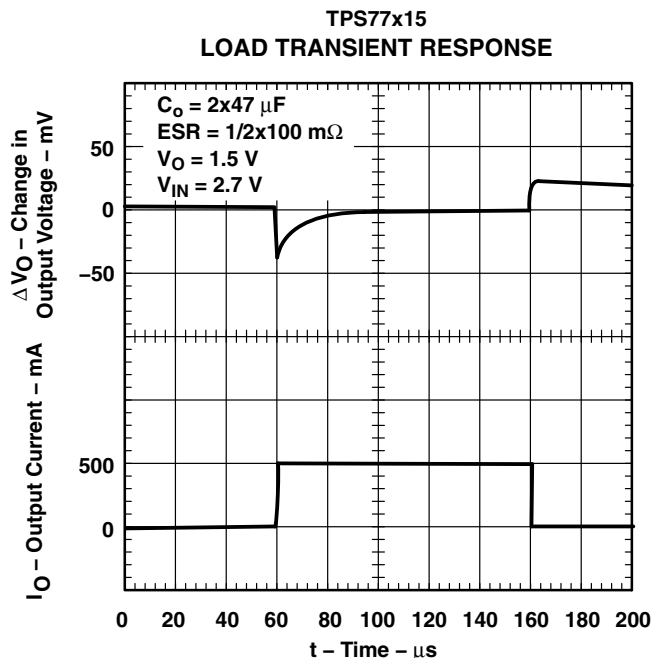


Figure 16

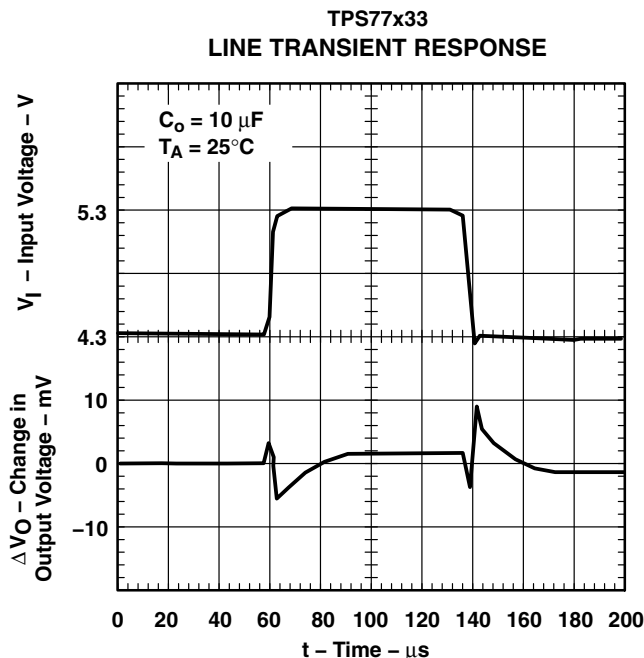


Figure 17

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

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TYPICAL CHARACTERISTICS

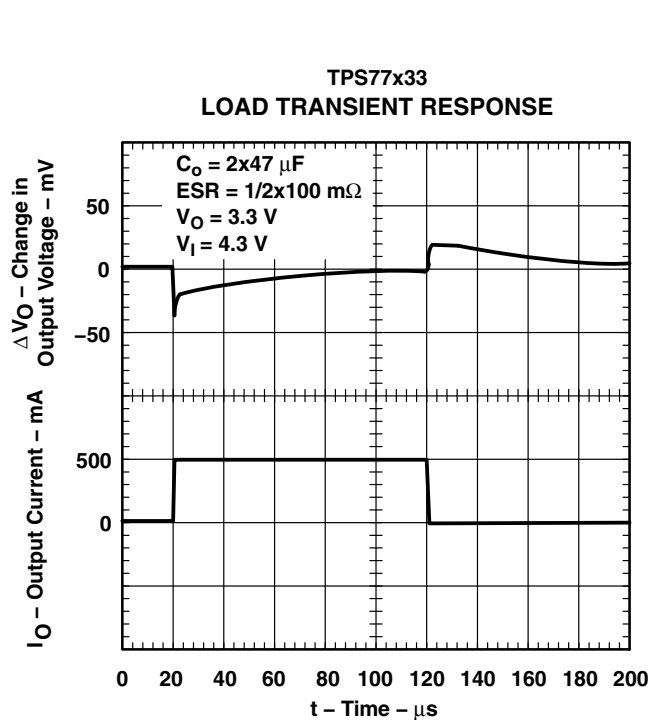


Figure 18

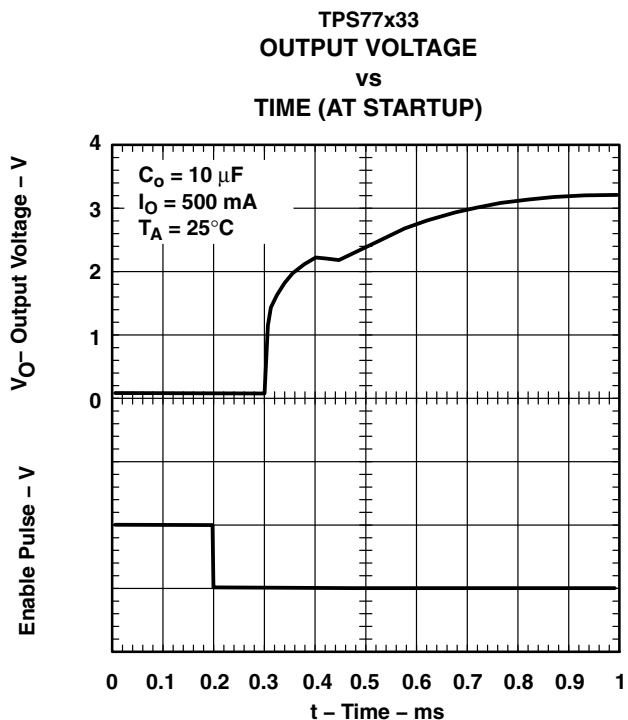


Figure 19

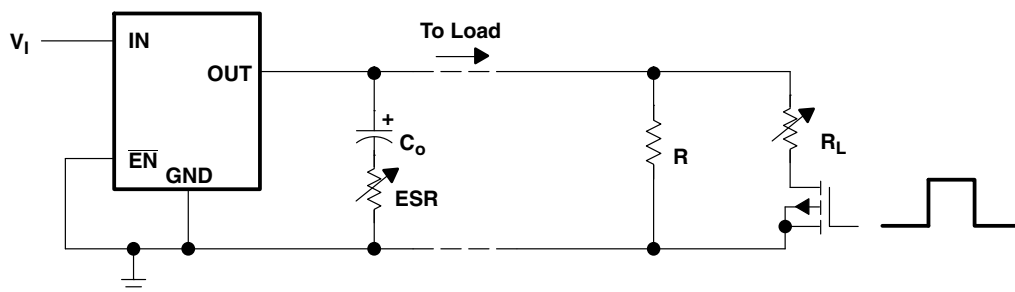


Figure 20. Test Circuit for Typical Regions of Stability (Figures 21 through 24) (Fixed Output Options)

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
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TYPICAL CHARACTERISTICS

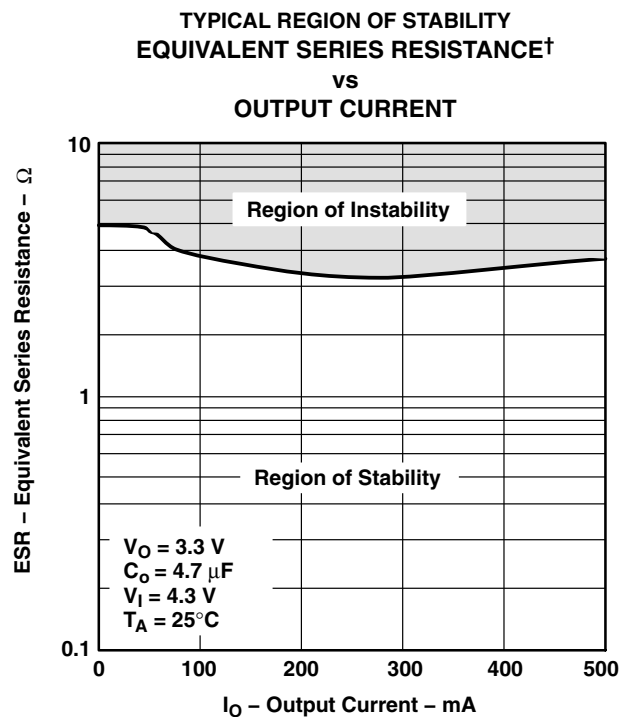


Figure 21

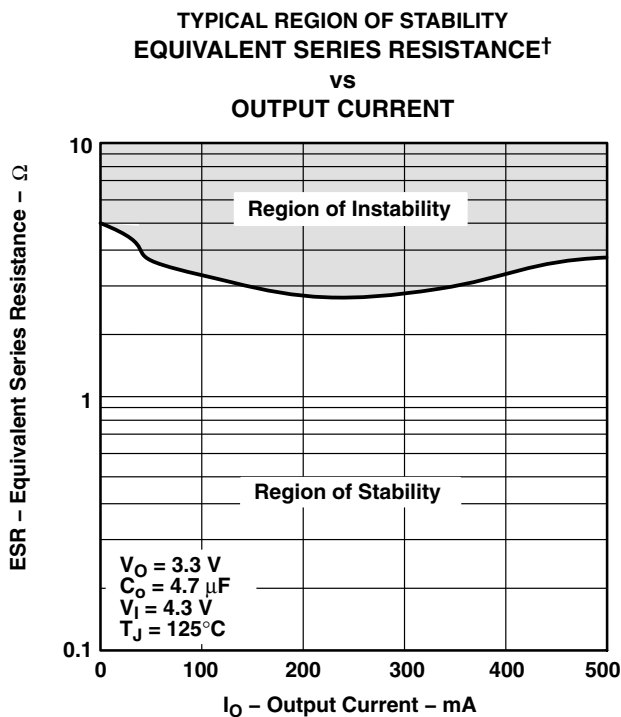


Figure 22

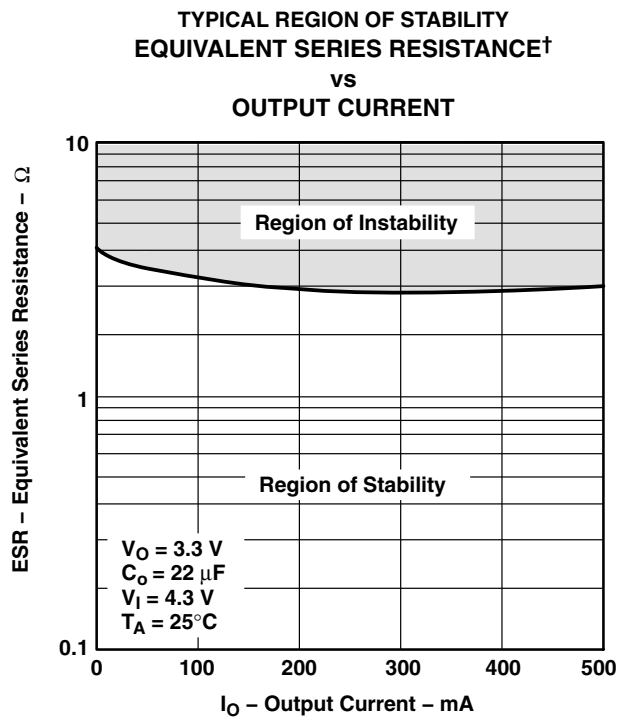


Figure 23

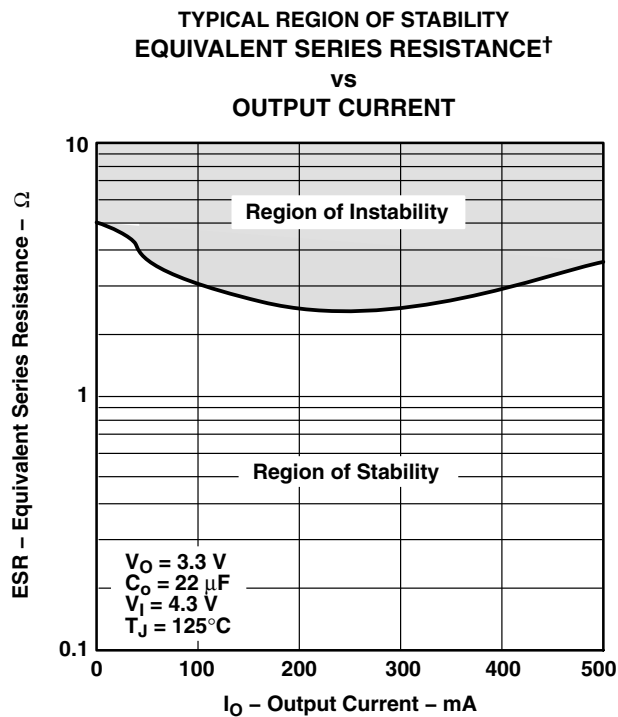


Figure 24

[†] Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O .

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH RESET OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

SGLS010B – MARCH 2003 – REVISED JUNE 2010

APPLICATION INFORMATION

The TPS775xx family includes five fixed-output voltage regulators (1.5 V, 1.6 V, 1.8 V, 2.5 V, and 3.3 V), and an adjustable regulator, the TPS77501 (adjustable from 1.5 V to 5.5 V).

device operation

The TPS775xx feature very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_O/\beta$). The TPS775xx use a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS775xx quiescent currents remain low even when the regulator drops out, eliminating both problems.

The TPS775xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to 2 μ A. If the shutdown feature is not used, \overline{EN} should be tied to ground.

minimum load requirements

The TPS775xx family is stable even at zero load; no minimum load is required for operation.

FB—pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option. The output voltage is sensed through a resistor divider network to close the loop as it is shown in Figure 26. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047 μ F or larger) improves load transient response and noise rejection if the TPS775xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS775xx require an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 μ F and the ESR (equivalent series resistance) must be between 50 m Ω and 1.5 Ω . Capacitor values 10 μ F or larger are acceptable, provided the ESR is less than 1.5 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.



APPLICATION INFORMATION

external capacitor requirements (continued)

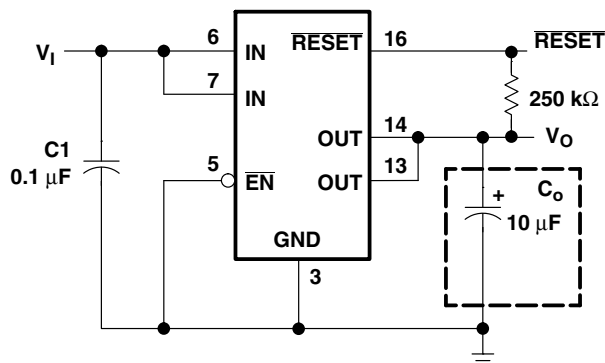


Figure 25. Typical Application Circuit (Fixed Versions)

programming the TPS77501 adjustable LDO regulator

The output voltage of the TPS77501 adjustable regulator is programmed using an external resistor divider as shown in Figure 26. The output voltage is calculated using:

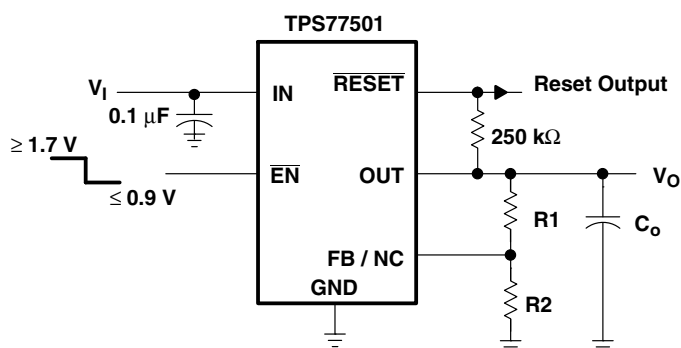
$$V_O = V_{\text{ref}} \times \left(1 + \frac{R1}{R2}\right) \quad (1)$$

Where:

$V_{\text{ref}} = 1.1834 \text{ V typ}$ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 10-μA divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 110 kΩ to set the divider current at approximately 10 μA and then calculate R1 using:

$$R1 = \left(\frac{V_O}{V_{\text{ref}}} - 1\right) \times R2 \quad (2)$$



OUTPUT VOLTAGE
PROGRAMMING GUIDE

| OUTPUT VOLTAGE | R1 | R2 | UNIT |
|----------------|-----|-----|------|
| 2.5 V | 121 | 110 | kΩ |
| 3.3 V | 196 | 110 | kΩ |
| 3.6 V | 226 | 110 | kΩ |
| 4.75 V | 332 | 110 | kΩ |

Figure 26. TPS77501 Adjustable LDO Regulator Programming

**TPS77501-EP, TPS77515-EP, TPS77516-EP, TPS77518-EP
TPS77525-EP, TPS77533-EP WITH $\overline{\text{RESET}}$ OUTPUT
FAST-TRANSIENT-RESPONSE 500-mA LOW-DROPOUT VOLTAGE REGULATORS**

SGLS010B – MARCH 2003 – REVISED JUNE 2010

APPLICATION INFORMATION

reset indicator

The TPS775xx features a $\overline{\text{RESET}}$ output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the $\overline{\text{RESET}}$ output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. $\overline{\text{RESET}}$ can be used to drive power-on reset circuitry or as a low-battery indicator. $\overline{\text{RESET}}$ does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low relative to its nominal regulated value (refer to timing diagram for start-up sequence).

regulator protection

The TPS775xx PMOS-pass transistors have a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS775xx also feature internal current limiting and thermal protection. During normal operation, the TPS775xx limit output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_D , which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{Jmax} - T_A}{R_{\theta JA}}$$

Where:

T_{Jmax} is the maximum allowable junction temperature.

$R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.



PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| TPS77501MPWPREP | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77501ME | Samples |
| TPS77501MPWPREG4 | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77501ME | Samples |
| TPS77515MPWPREP | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77515ME | Samples |
| TPS77518MPWPREP | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77518ME | Samples |
| TPS77525MPWPREP | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77525ME | Samples |
| TPS77533MPWPREP | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77533ME | Samples |
| V62/03631-01XE | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77501ME | Samples |
| V62/03631-02XE | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77515ME | Samples |
| V62/03631-04XE | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77518ME | Samples |
| V62/03631-05XE | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77525ME | Samples |
| V62/03631-06XE | ACTIVE | HTSSOP | PWP | 20 | 2000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -55 to 125 | 77533ME | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS77501MPWPREP | HTSSOP | PWP | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| TPS77515MPWPREP | HTSSOP | PWP | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| TPS77518MPWPREP | HTSSOP | PWP | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| TPS77525MPWPREP | HTSSOP | PWP | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| TPS77533MPWPREP | HTSSOP | PWP | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS77501MPWPREP | HTSSOP | PWP | 20 | 2000 | 350.0 | 350.0 | 43.0 |
| TPS77515MPWPREP | HTSSOP | PWP | 20 | 2000 | 350.0 | 350.0 | 43.0 |
| TPS77518MPWPREP | HTSSOP | PWP | 20 | 2000 | 350.0 | 350.0 | 43.0 |
| TPS77525MPWPREP | HTSSOP | PWP | 20 | 2000 | 350.0 | 350.0 | 43.0 |
| TPS77533MPWPREP | HTSSOP | PWP | 20 | 2000 | 350.0 | 350.0 | 43.0 |

PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

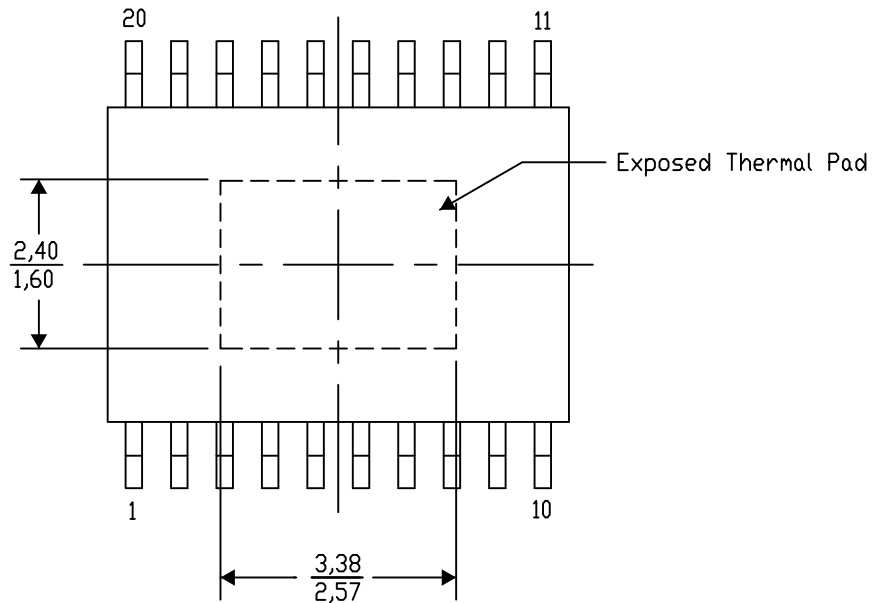
PWP (R-PDSO-G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



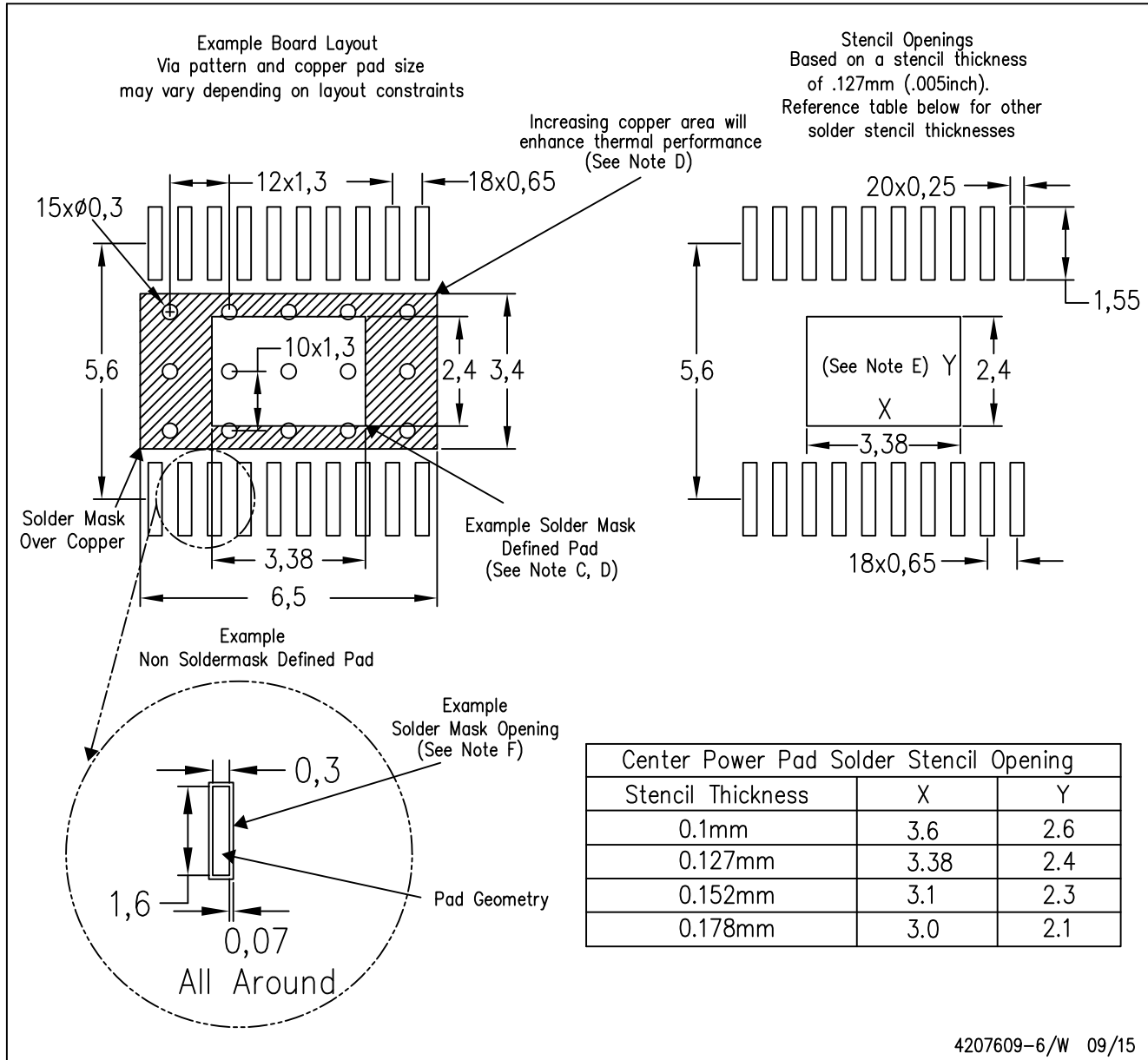
4206332-13/AO 01/16

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

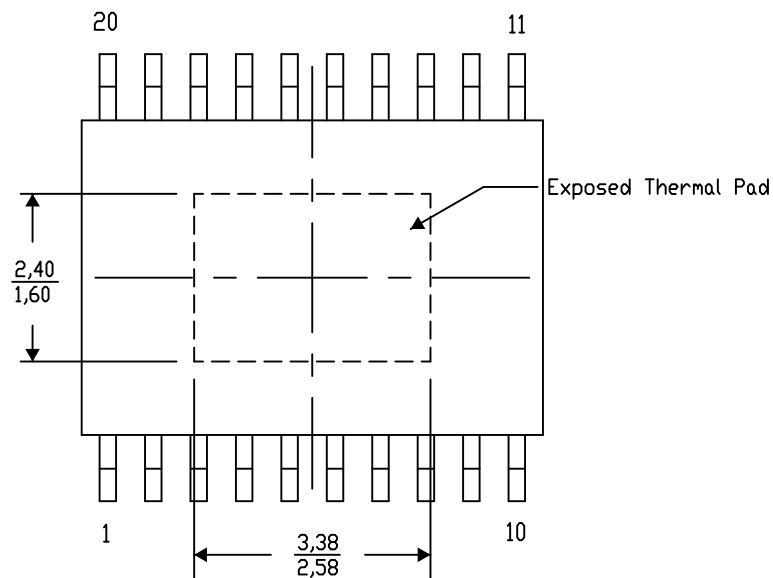
PWP (R-PDSO-G20) PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



4206332–21/AO 01/16

NOTE: A. All linear dimensions are in millimeters

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